

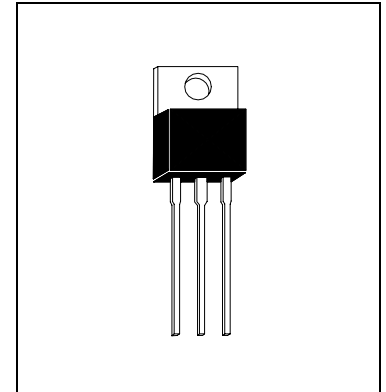


H2N6388

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The H2N6388 is designed for general-purpose amplifier and switching applications.



Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
 - Storage Temperature -55 ~ +150 °C
 - Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 - Total Power Dissipation (Tc=25°C) 65 W
 - Total Power Dissipation (Ta=25°C) 2 W
- Maximum Voltages and Currents
 - BVCBO Collector to Base Voltage 80 V
 - BVCEO Collector to Emitter Voltage 80 V
 - BVEBO Emitter to Base Voltage 5 V
 - IC Collector Current 10 A

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	80	-	-	V	IC=1mA, IE=0
*BVCEO	80	-	-	V	IC=200mA, IB=0
ICBO	-	-	100	uA	VCB=160V, IE=0
IEBO	-	-	5	mA	VEB=5V, IC=0
ICEO	-	-	1	mA	VCE=80V, IB=0
ICEV	-	-	300	uA	VCE=80V, VBE(off)=1.5V
*VCE(sat)1	-	-	2	V	IC=5A, IB=10mA
*VCE(sat)2	-	-	3	V	IC=10A, IB=100mA
*VCE(sat)3	-	1.5	-	V	IC=5A, IB=2.5mA
*VBE(sat)	-	2	-	V	IC=5A, IB=5mA
VBE(on)1	-	-	2.8	V	IC=5A, VCE=3V
VBE(on)2	-	-	4.5	V	IC=10A, VCE=3V
*hFE1	1	-	20	K	IC=5A, VCE=3V
*hFE2	100	-	-		IC=10A, VCE=3V
VFEC	-	3	-	V	IC=5A
Cob	-	-	200	pF	VCB=10V, IE=0

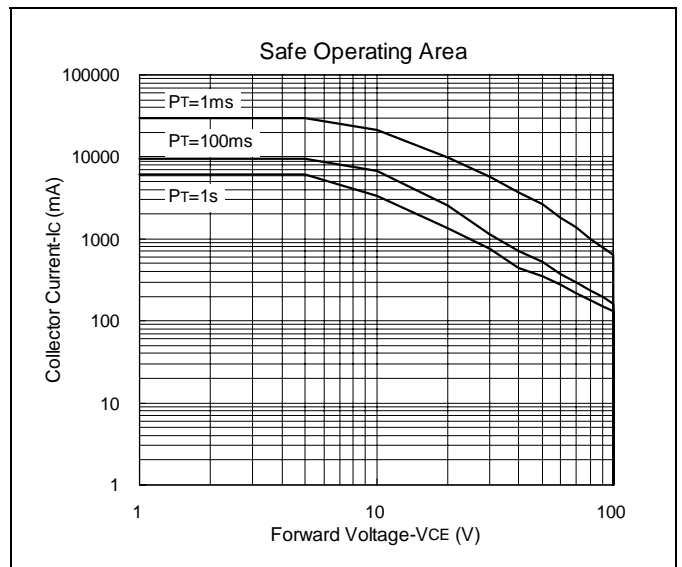
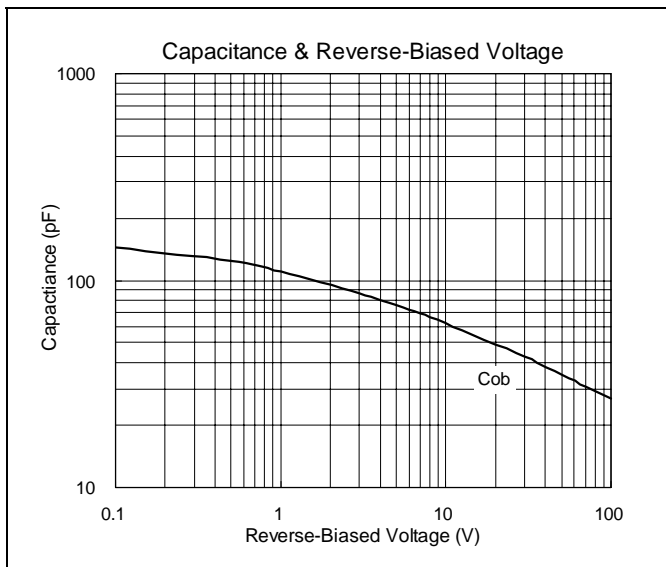
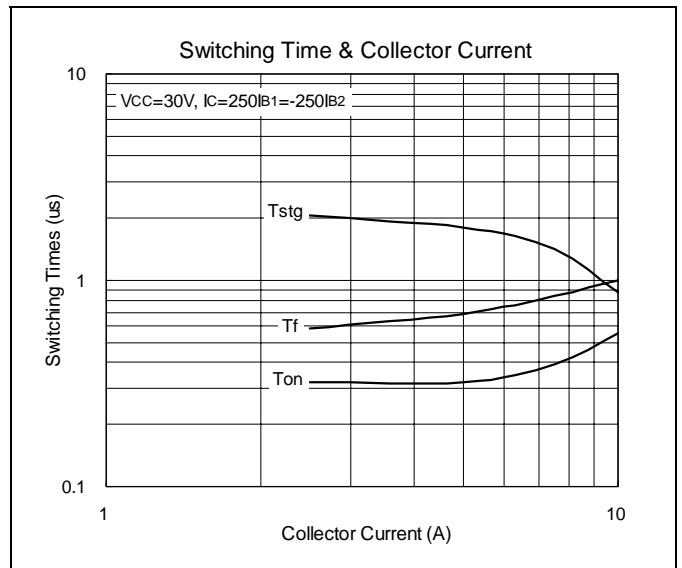
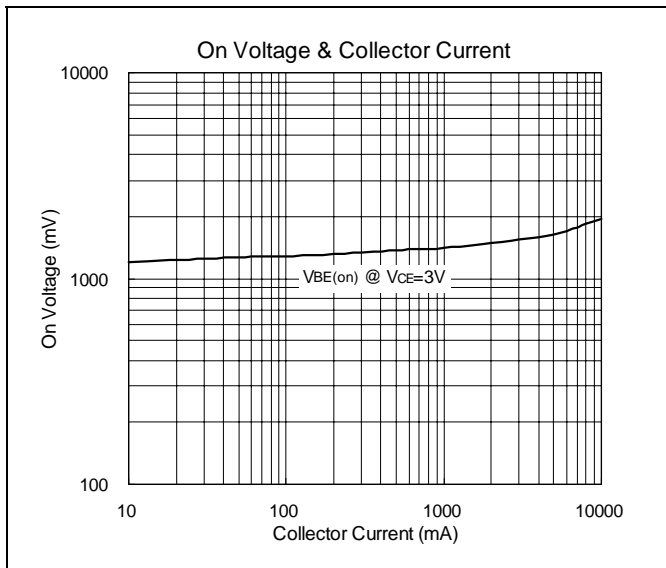
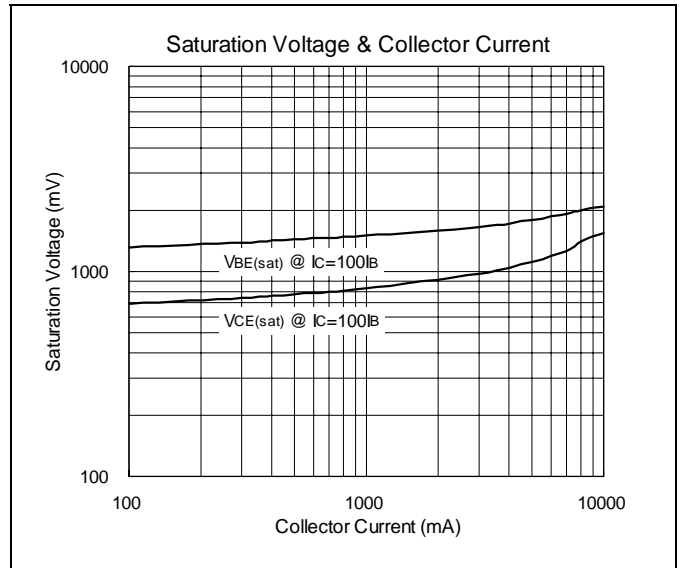
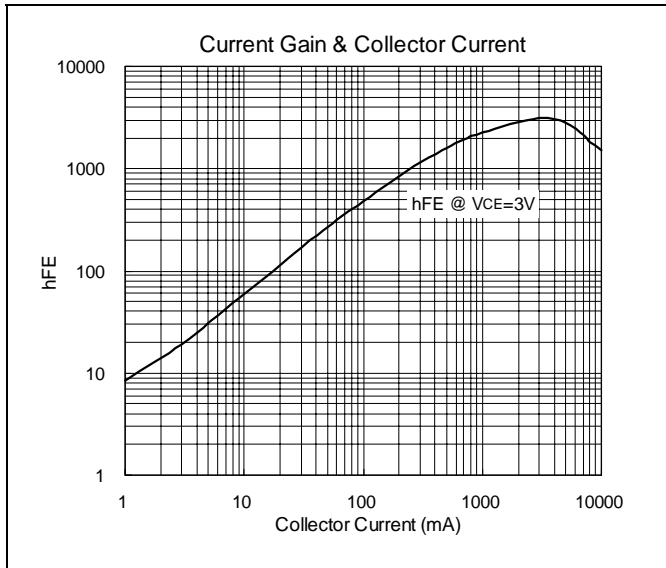
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

Classification of

Rank	hFE1	VCE(sat)1	VCE(sat)3	VBE(sat)	VFEC
KC	2-20K	<1.3V	<1.5V	<2.0V	<3.0V
Normal	1-20K	<2.0V	-	-	-

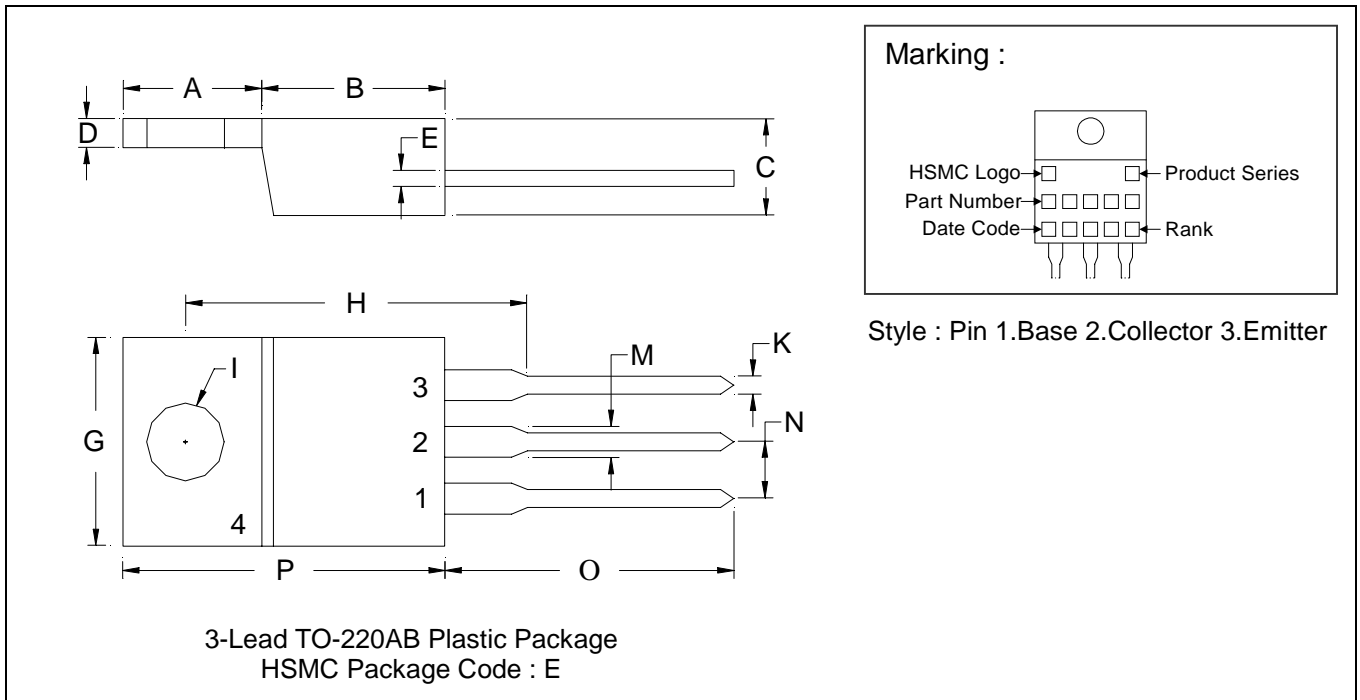


Characteristics Curve





TO-220AB Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2197	0.2949	5.58	7.49	I	-	*0.1508	-	*3.83
B	0.3299	0.3504	8.38	8.90	K	0.0295	0.0374	0.75	0.95
C	0.1732	0.185	4.40	4.70	M	0.0449	0.0551	1.14	1.40
D	0.0453	0.0547	1.15	1.39	N	-	*0.1000	-	*2.54
E	0.0138	0.0236	0.35	0.60	O	0.5000	0.5618	12.70	14.27
G	0.3803	0.4047	9.66	10.28	P	0.5701	0.6248	14.48	15.87
H	-	*0.6398	-	*16.25					

Notes : 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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